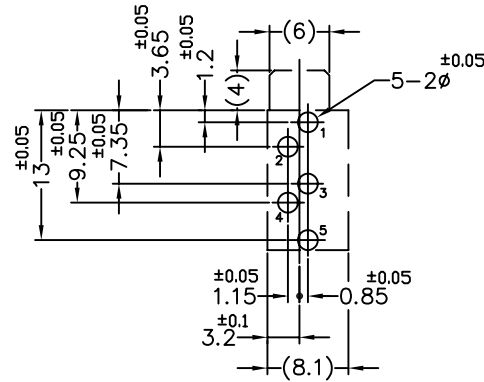
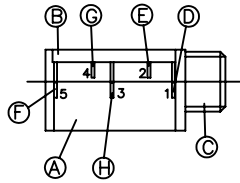
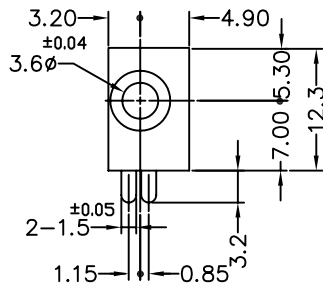
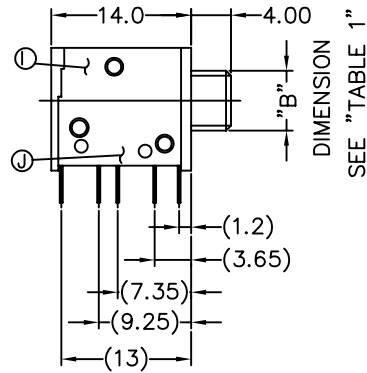
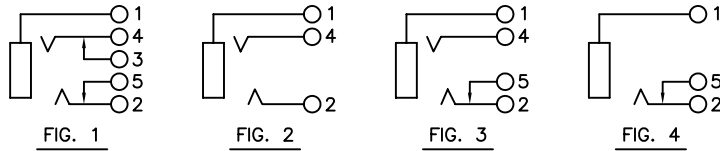


REV.	ECN NO OR DESCRIPTION	REVISED	DATE
C	ECN NO: 920008	EVEN	2005.10.11



RECOMMENDED P.C.B LAYOUT
SOLDERING SIDE

CIRCUIT:



DRAWING NO.	CIRCUIT FIG.	"DIM "B"	TIP SPRING	RING SPRING	SHUNT TERMINAL-A	SHUNT TERMINAL-B
2SJ-03723T33	FIG. 1	M6xP0.5	1	1	1	1
2SJ-03723N33	FIG. 1	6 ϕ ±0.1	1	1	1	1
2SJ-03733T33	FIG. 2	M6xP0.5	1	1		
2SJ-03733N33	FIG. 2	6 ϕ ±0.1	1	1		
2SJ-03743T33	FIG. 3	M6xP0.5	1	1	1	
2SJ-03743N33	FIG. 3	6 ϕ ±0.1	1	1	1	
2SJ-03753T33	FIG. 4	M6xP0.5	1		1	
2SJ-03753N33	FIG. 4	6 ϕ ±0.1	1		1	

SPECIFICATIONS :

- CURRENT CARRYING RATING :24V DC 2AMP MAX.
- MARKING :MARK "SWITCHCRAFT" ON REAR OF CONNECTOR.
- SPECIFICATION SEE "SPECIFICATIONS OF 2SJ-0372 SERIES"
- SOLDER HEAT RESISTANCE: WAVE SOLDERING 260°C 10 SECS.
- TO CONFORM TO THE "SE-01-001" & "ROHS DIRECTIVE"
- GREEN PRODUCT IDENTIFICATION MARK IN JACK:
- GREEN PRODUCT IDENTIFICATION LABEL IN PACKING: **G.P. PASS**
- FOR WAVE SOLDERING LEAD-FREE PROCESS.

J	COIL SPRING-B	1	SUS	
I	COIL SPRING-A	1	SUS	
H	SHUNT TERMINAL-B	*	BRASS 0.3t	SILVER 20 μ m PLATING OVER COPPER 60 μ m & NICKEL 60 μ m PLATING
G	RING SPRING	*	BRASS 0.25t	SILVER 20 μ m PLATING OVER COPPER 60 μ m & NICKEL 60 μ m PLATING
F	SHUNT TERMINAL-A	*	BRASS 0.3t	SILVER 20 μ m PLATING OVER COPPER 60 μ m & NICKEL 60 μ m PLATING
E	TIP SPRING	*	BRASS 0.3t	SILVER 20 μ m PLATING OVER COPPER 60 μ m & NICKEL 60 μ m PLATING
D	EARTH TERMINAL	1	BRASS 0.3t	SILVER 20 μ m PLATING OVER COPPER 60 μ m & NICKEL 60 μ m PLATING
C	METAL	1	BRASS	NICKEL PLATING
B	COVER	1	POLYCARBONATE UL 94V-0	TRANSPARENT
A	BODY	1	PBT UL 94V-0	BLACK COLOR
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR

UNLESS OTHERWISE SPECIFIED TOLERANCES

Singatron Enterprise Co., Ltd.
信音企業股份有限公司

DECIMALS:	ANGLES:	TITLE	3.5 ϕ PHONE JACK	
X :±0.5	X :±2'	DWN	EVEN 2005.10.8	PART NO. 2SJ-037□3□33
X.X :±0.3	X.X :±1'	CHKD	KAN 2005.10.12	SCALE:2/1 UNIT: mm
X.XX :±0.2		APVD	KAN 2005.10.13	SIZE: A3 SHEET:1 OF 1 REV: C
CUSTOMER COPY				